

MOSFET - N 沟道, POWERTRENCH®

75 V, 100 A, 3.7 m Ω

FDMS037N08B

说明

此 N 沟道 MOSFET 采用安森美 (onsemi)先进的 POWER-TRENCH 工艺生产,这一先进工艺是专为最大限度地降低通态电阻并保持卓越开关性能而定制的。

特性

- $R_{DS(on)} = 3.01 \text{ m}\Omega$ (典型值) @ $V_{GS} = 10 \text{ V}$, $I_D = 50 \text{ A}$
- 低 FOM R_{DS(on)}*Q_G
- 低反向恢复电荷, Q_{rr} = 80 nC
- 软反向恢复体二极管
- 可实现高效同步整流
- 快速开关速度
- 100% 经过 UIL 测试
- 符合 RoHS 标准

应用

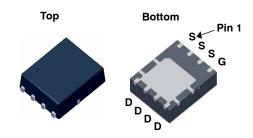
- 用于 ATX/ 服务器 / 电信 PSU 的同步整流
- 电池保护电路
- DC 电机驱动和不间断电源

MOSFET 最大额定值 (T_A = 25°C 除非另有说明。)

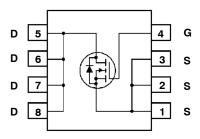
Symbol	Parameter	Value	Unit
符号	参数	Value	单位
V _{DSS}	漏极一源极电压	75	V
V _{GSS}	栅极一源极电压	±20	V
I _D	漏极电流 - 连续 (T _C = 25°C) - 连续 (T _C = 25°C, 硅限制) - 连续 (T _A = 25°C) (说明 1a)	100 128 19.9	Α
I _{DM}	漏极电流 - 脉冲 (说明 2)	400	Α
E _{AS}	单脉冲雪崩能量 (说明 3)	180.6	mJ
P _D	功耗 (T _C = 25°C)	104.2	W
	功耗 (T _A = 25°C) (说明 1a)	0.83	
T _J , T _{stg}	工作和存储温度范围	-55 至 +150	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. (参考译文)

如果电压超过最大额定值表中列出的值范围,器件可能会损坏。如果超过任何 这些限值,将无法保证器件功能,可能会导致器件损坏,影响可靠性。



PQFN8 5X6, 1.27P (Power 56) CASE 483AE



MARKING DIAGRAM

&Z&3&K FDMS O 037N08B

&Z = Assembly Plant Code&3 = Numeric Date Code&K = 2-Digit Lot Code

FDMS037N08B = Specific Device Code

ORDERING INFORMATION

Device	Package	Shipping [†]
FDMS037N08B	PQFN-8 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

热性能

符号	参数	Value	单位
$R_{\theta JC}$	结至外壳热阻最大值	1.2	°C ///
$R_{\theta JA}$	结至环境热阻最大值 (说明 1a)	50	°C/W

关断特性 (T」 = 25°C 除非另有说明。)

	(IJ = 25 · U 除非力有 说奶。)	测→ <i>P</i> / →	最小值	曲型性	最大值	¥ <i>1</i> >-
符号	参数	测试条件	取小但	典型值	取入徂	单位
关断特性		L	1	1	1	.,
BV _{DSS}	漏极一源极击穿电压	I _D = 250 μA, V _{GS} = 0 V	75	_	-	V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	漏极一源极击穿电压 	I _D = 250 μA, 推荐选用 25°C	_	39	_	mV/°C
	泰柳林内厅没机内达	V _{DS} = 60 V, V _{GS} = 0 V	_			^
I _{DSS}	零栅极电压漏极电流			_	1	μΑ
I _{GSS}	栅极- 体漏电流	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±100	nA
导通特性	T		1	T	T	T I
V _{GS(th)}	栅极阈值电压	$V_{GS} = V_{DS}$, $I_D = 250 \mu A$	2.5	_	4.5	V
R _{DS(on)}	漏极至源极静态导通电阻	V _{GS} = 10 V, I _D = 50 A	_	3.01	3.7	mΩ
9FS	正向跨导	$V_{DS} = 10 \text{ V}, I_D = 50 \text{ A}$	_	108	_	S
动态特性		_				
C _{iss}	输入电容	$V_{DS} = 37.5 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	4550	5915	pF
C _{oss}	输出电容		-	1060	1380	pF
C _{rss}	反向传输电容		-	30.2	45	pF
C _{oss} (er)	能量相关输出电容	V _{DS} = 37.5 V, V _{GS} = 0 V	_	1702	-	pF
Q _{g(tot)}	10 V 的栅极电荷总量	V _{DS} = 37.5 V, I _D = 50 A	_	76.8	100	nC
Q _{gs}	栅极 - 源极栅极电荷	V _{GS} = 0 V, 至 10 V (说明 4)	_	27.5	_	nC
Q _{gd}	栅极 - 漏极 " 米勒 " 电荷	7	_	17.4	_	nC
V _{plateau}	栅极平台电压	7	_	5.1	_	V
Q _{sync}	总栅极电荷同步	V _{DS} = 0 V, I _D = 50 A	_	66.3	_	nC
Q _{oss}	输出电荷	V _{DS} = 37.5 V, V _{GS} = 0 V	_	74.6	_	nC
ESR	等效串联电阻	f = 1 MHz	_	1.28	_	Ω
漏极 - 源机			•	•	•	•
t _{d(on)}	导通延迟时间	$V_{DD} = 37.5 \text{ V}, I_D = 50 \text{ A},$	-	34.9	80	ns
t _r	开通上升时间	V_{GS} = 10 V, R_G = 4.7 Ω (说明 4)	_	20.1	50	ns
t _{d(off)}	关断延迟时间	1	_	55.3	120	ns
t _f	关断下降时间		_	19.4	49	ns
I _S	漏极 - 源极二极管最大正向连续电流		_	_	100	Α
I _{SM}	漏极 - 源极二极管最大正向脉冲电流		_	_	400	Α
V _{SD}	漏极 - 源极二极管正向电压	V _{GS} = 0 V, I _{SD} = 50 A	_	_	1.3	V
t _{rr}	反向恢复时间	$V_{GS} = 0 \text{ V, } I_{SD} = 50 \text{ A}$ $dI_F/dt = 100 \text{ A/}\mu\text{s}$	-	66.8	_	ns
Q _{rr}	反向恢复电荷		_	84	-	nC
<u> </u>	<u> </u>		1	l	l	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

(参考译文)
除非另有说明,"电气特性"表格中列出的是所列测试条件下的产品性能参数。如果在不同条件下运行,产品性能可能与"电气特性"表格中所列性能参数不一致。

NOTES:

1. $R_{\theta JA}$ 取决于安装在 FR-4材质 1.5 x 1.5 in. 电路板上 1 in 2 2 盎司铜焊盘上的器件。 $R_{\theta JC}$ 通过设计保证 而 $R_{\theta CA}$ 取决于用户的电路板设计。



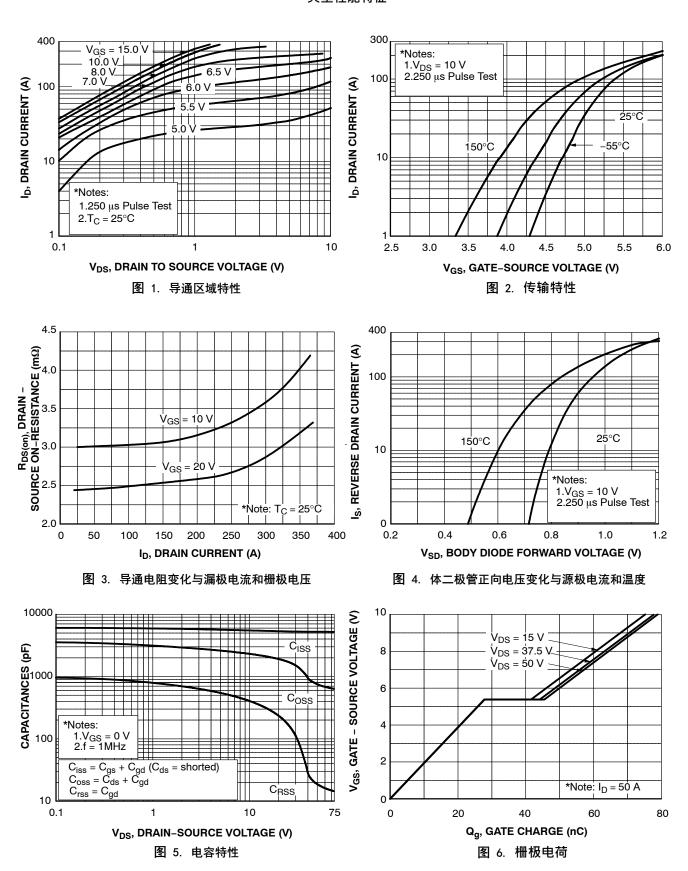
a).50 °C/W, 安装于 1 in² 2 盎司铜焊盘。



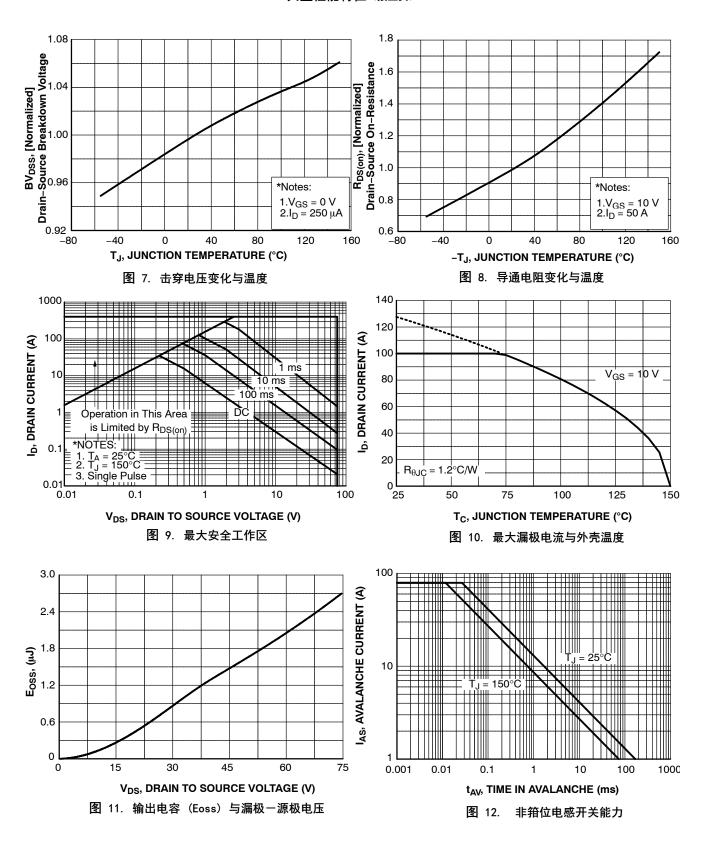
b).125 °C/W, 安装于 最小尺寸的 2 盎司铜焊盘。

- 2. 重复额定值: 脉冲宽度受限于最大结温。 3. L = 0.3 mH, I_{AS} = 34.7 A, 开始 T_J = 25°C. 4. 本质上独立于工作温度的典型特性。

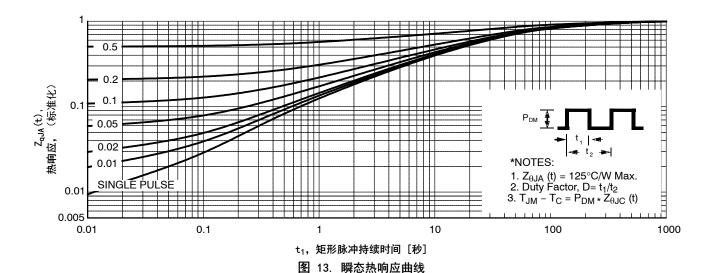
典型性能特征



典型性能特征 (接上页)



典型性能特征(接上页)



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典型性能特征

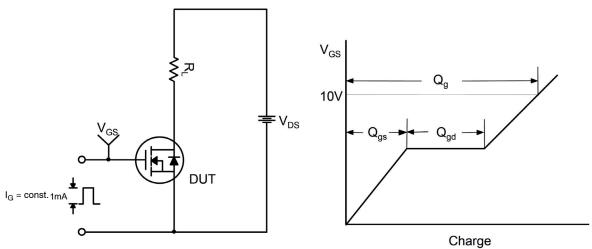


图 14. 栅极电荷测试电路与波形

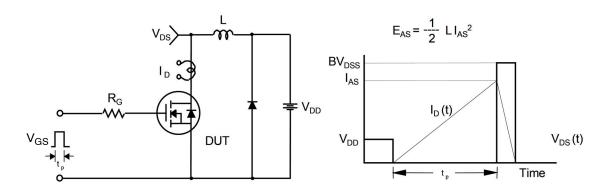
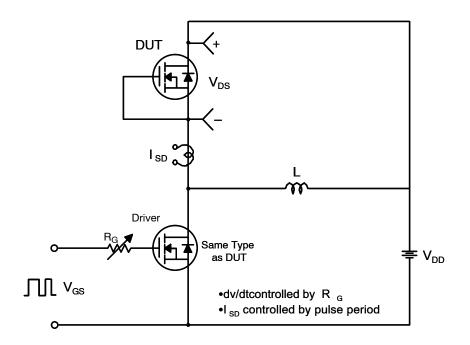


图 15. 非箝位电感开关测试电路与波形



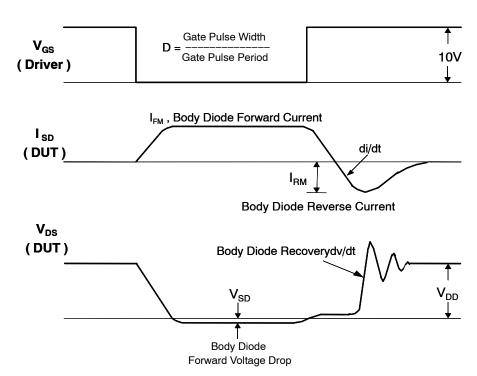


图 16. 二极管恢复 dv/dt 峰值测试电路与波形

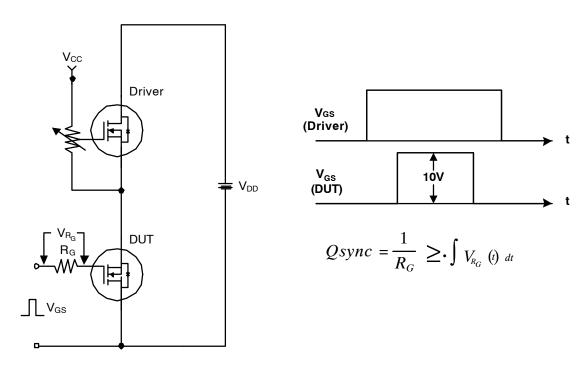


图 17. 总栅极电荷 Qsync 测试电路与波形

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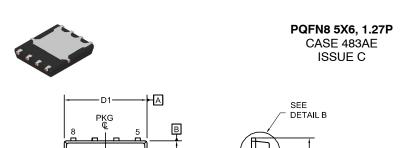
PKG &

PIN 1

AREA

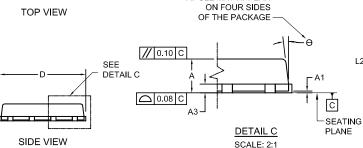


DATE 21 JAN 2022



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- 3. COPLANARITY APPLIES TO THE EXPOSED PADS AS WELL AS THE TERMINALS.
- 4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.
- 5. SEATING PLANE IS DEFINED BY THE TERMINALS. "A1" IS DEFINED AS THE DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 6. IT IS RECOMMENDED TO HAVE NO TRACES OR VIAS WITHIN THE KEEP OUT AREA.

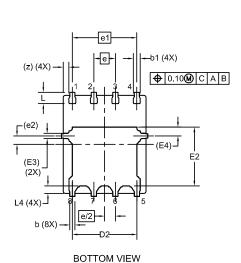


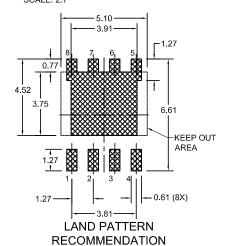
OPTIONAL DRAFT

ANGLE MAY APPEAR

ل 22 **DETAIL B**

SCALE: 2:1





*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

DIM	M	IILLIMETERS		
J	MIN.	NOM.	MAX.	
Α	0.90	1.00	1.10	
A1	0.00	-	0.05	
b	0.21	0.31	0.41	
b1	0.31	0.41	0.51	
А3	0.15	0.25	0.35	
D	4.90	5.00	5.20	
D1	4.80	4.90	5.00	
D2	3.61	3.82	3.96	
Е	5.90	6.15	6.25	
E1	5.70	5.80	5.90	
E2	3.38	3.48	3.78	
E3	(0.30 REF		
E4	0.52 REF			
е	1.27 BSC			
e/2	0.635 BSC			
e1	3.81 BSC			
e2	0.50 REF			
L	0.51	0.66	0.76	
L2	0.05	0.18	0.30	
L4	0.34	0.44	0,54	
Z	0.34 REF			
Θ	0°	-	12°	

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